

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10553470
<b>Filing Date:</b>	19-May-2006
<b>Title of Invention:</b>	Monitoring the reduction in thickness as material is removed from a wafer composite and test structure for monitoring removal of material
<b>First Named Inventor/Applicant Name:</b>	Ralf Lerner
<b>Filer:</b>	Dwight M. Benner/Patricia Hodge
<b>Attorney Docket Number:</b>	60291.000041

Filed as Large Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

**Post-Allowance-and-Post-Issuance:**

**Extension-of-Time:**

Extension - 1 month with \$0 paid	1251	1	120	120
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	810	810
<b>Total in USD (\$)</b>				<b>930</b>